

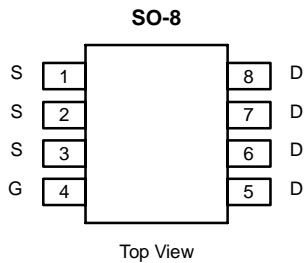


N-Channel Reduced Q_g , Fast Switching MOSFET

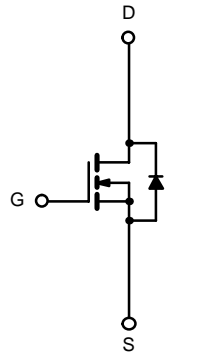
PRODUCT SUMMARY

| V_{DS} (V) | $r_{DS(on)}$ (Ω) | I_D (A) |
|--------------|---------------------------|-----------|
| 60 | 0.022 @ $V_{GS} = 10$ V | 8.5 |
| | 0.031 @ $V_{GS} = 4.5$ V | 7.2 |

175°C Rated
Maximum Junction Temperature
TrenchFET®
Power MOSFETs



Ordering Information: Si4850EY
Si4850EY-T1 (with Tape and Reel)



N-Channel MOSFET

ABSOLUTE MAXIMUM RATINGS ($T_A = 25^\circ\text{C}$ UNLESS OTHERWISE NOTED)

| Parameter | | Symbol | 10 secs | Steady State | Unit |
|--|-----------------------|-----------------------------------|------------|--------------|------|
| Drain-Source Voltage | | V _{DS} | 60 | | V |
| Gate-Source Voltage | | V _{GS} | ± 20 | | |
| Continuous Drain Current (T _J = 175°C) ^a | T _A = 25°C | I _D | 8.5 | 6.0 | A |
| | T _A = 70°C | | 7.1 | 5.0 | |
| Pulsed Drain Current | | I _{DM} | 40 | | |
| Avalanche Current ^b | | I _{AS} | 15 | | |
| Repetitive Avalanche Energy ^b | | E _{AS} | 11 | | mJ |
| Maximum Power Dissipation ^a | T _A = 25°C | P _D | 3.3 | 1.7 | W |
| | T _A = 70°C | | 2.3 | 1.2 | |
| Operating Junction and Storage Temperature Range | | T _J , T _{stg} | -55 to 175 | | °C |

THERMAL RESISTANCE RATINGS

| Parameter | | Symbol | Typical | Maximum | Unit |
|--|-----------------|------------|---------|---------|--------------------|
| Maximum Junction-to-Ambient ^a | $t \leq 10$ sec | R_{thJA} | 36 | 45 | $^\circ\text{C/W}$ |
| | Steady State | | 75 | 90 | |
| Maximum Junction-to-Foot (Drain) | Steady State | R_{thJF} | 17 | 20 | |

Notes

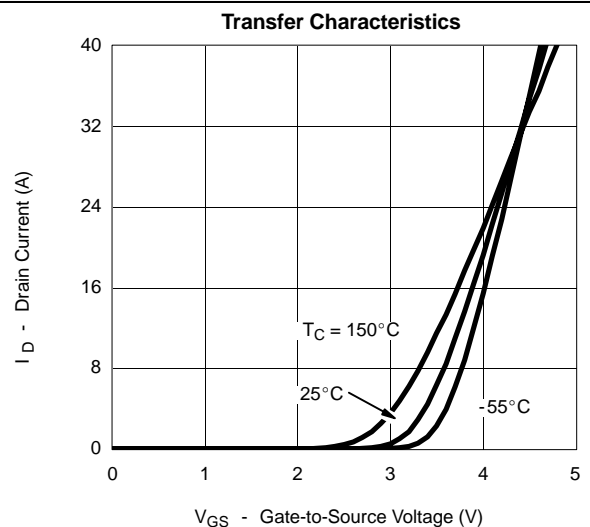
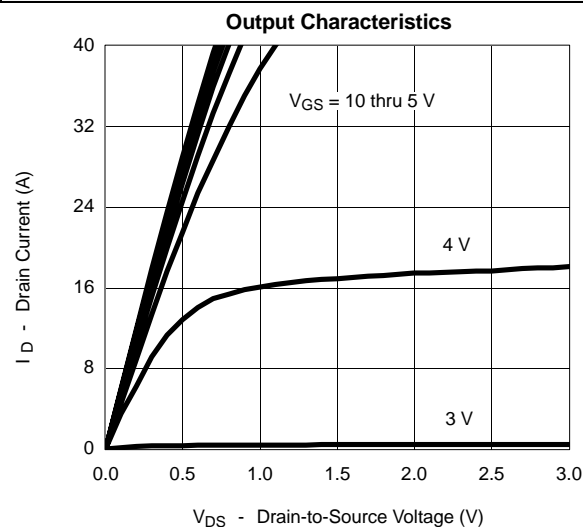
- Surface Mounted on 1" x 1" FR4 Board.
- Guaranteed by design, not subject to production testing.

SPECIFICATIONS ($T_J = 25^\circ\text{C}$ UNLESS OTHERWISE NOTED)

| Parameter | Symbol | Test Condition | Min | Typ | Max | Unit |
|---|---------------|--|-----|-------|-----------|---------------|
| Static | | | | | | |
| Drain-Source Breakdown Voltage | $V_{(BR)DSS}$ | $V_{GS} = 0\text{ V}, I_D = 250\text{ }\mu\text{A}$ | 60 | | | V |
| Gate Threshold Voltage | $V_{GS(th)}$ | $V_{DS} = V_{GS}, I_D = 250\text{ }\mu\text{A}$ | 1 | | | V |
| Gate-Body Leakage | I_{GSS} | $V_{DS} = 0\text{ V}, V_{GS} = \pm 20\text{ V}$ | | | ± 100 | nA |
| Zero Gate Voltage Drain Current | I_{DSS} | $V_{DS} = 60\text{ V}, V_{GS} = 0\text{ V}$ | | | 1 | μA |
| | | $V_{DS} = 60\text{ V}, V_{GS} = 0\text{ V}, T_J = 55^\circ\text{C}$ | | | 20 | |
| On-State Drain Current ^a | $I_{D(on)}$ | $V_{DS} \geq 5\text{ V}, V_{GS} = 10\text{ V}$ | 40 | | | A |
| Drain-Source On-State Resistance ^a | $r_{DS(on)}$ | $V_{GS} = 10\text{ V}, I_D = 6.0\text{ A}$ | | 0.018 | 0.022 | Ω |
| | | $V_{GS} = 10\text{ V}, I_D = 6.0\text{ A}, T_J = 125^\circ\text{C}$ | | 0.031 | 0.037 | |
| | | $V_{GS} = 10\text{ V}, I_D = 6.0\text{ A}, T_J = 175^\circ\text{C}$ | | 0.039 | 0.047 | |
| | | $V_{GS} = 4.5\text{ V}, I_D = 5.1\text{ A}$ | | 0.025 | 0.031 | |
| Forward Transconductance ^a | g_{fs} | $V_{DS} = 15\text{ V}, I_D = 6.0\text{ A}$ | | 25 | | S |
| Diode Forward Voltage ^a | V_{SD} | $I_S = 1.7\text{ A}, V_{GS} = 0\text{ V}$ | | 0.8 | 1.2 | V |
| Dynamic^b | | | | | | |
| Total Gate Charge | Q_g | $V_{DS} = 30\text{ V}, V_{GS} = 10\text{ V}, I_D = 6.0\text{ A}$ | | 18 | 27 | nC |
| Gate-Source Charge | Q_{gs} | | | 3.4 | | |
| Gate-Drain Charge | Q_{gd} | | | 5.3 | | |
| Gate Resistance | R_g | $V_{GS} = 0.1\text{ V}, f = 5\text{ MHz}$ | 0.5 | 1.4 | 2.4 | Ω |
| Turn-On Delay Time | $t_{d(on)}$ | $V_{DD} = 30\text{ V}, R_L = 30\text{ }\Omega$ $I_D \cong 1\text{ A}, V_{GEN} = 10\text{ V}, R_G = 6\text{ }\Omega$ | | 10 | 20 | ns |
| Rise Time | t_r | | | 10 | 20 | |
| Turn-Off Delay Time | $t_{d(off)}$ | | | 25 | 50 | |
| Fall Time | t_f | | | 12 | 24 | |
| Source-Drain Reverse Recovery Time | t_{rr} | $I_F = 1.7\text{ A}, di/dt = 100\text{ A}/\mu\text{s}$ | | 50 | 80 | |

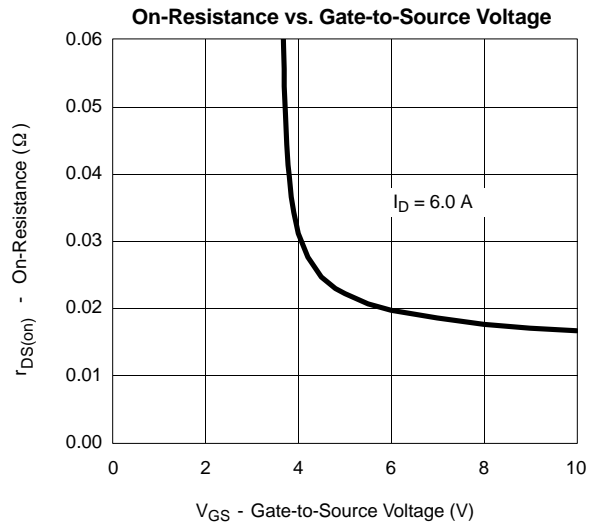
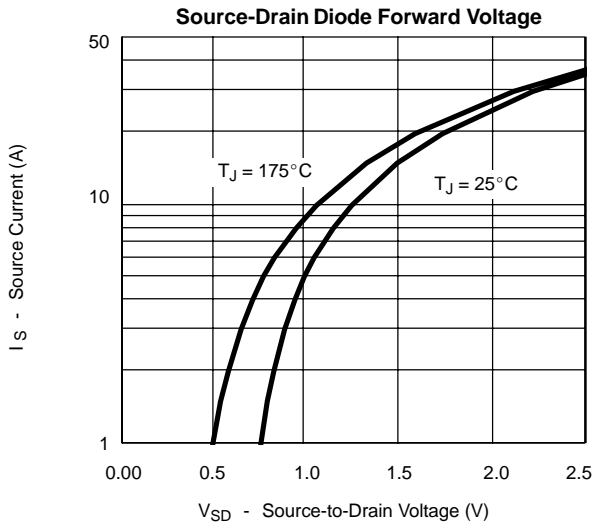
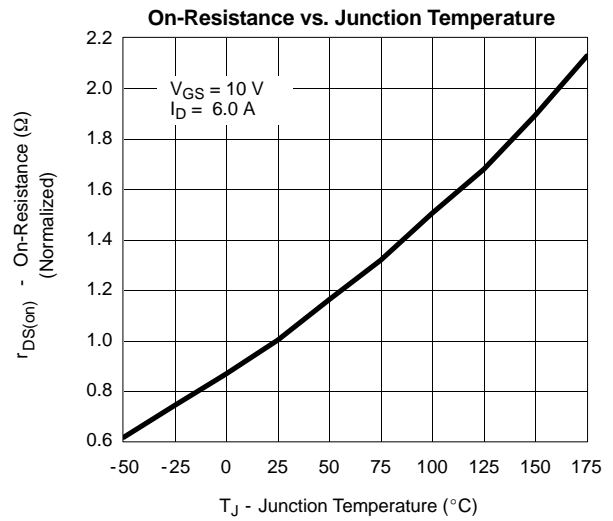
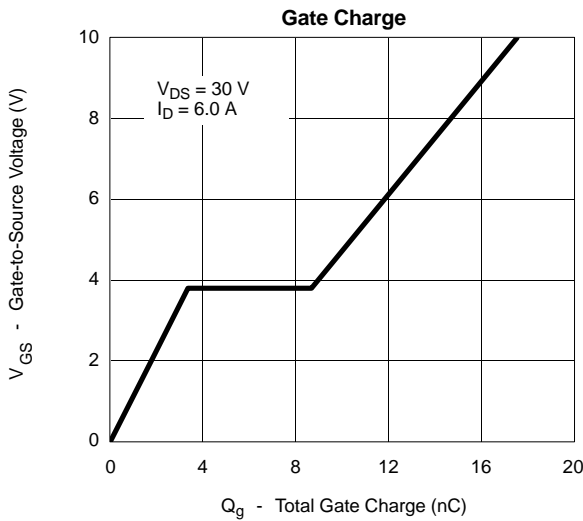
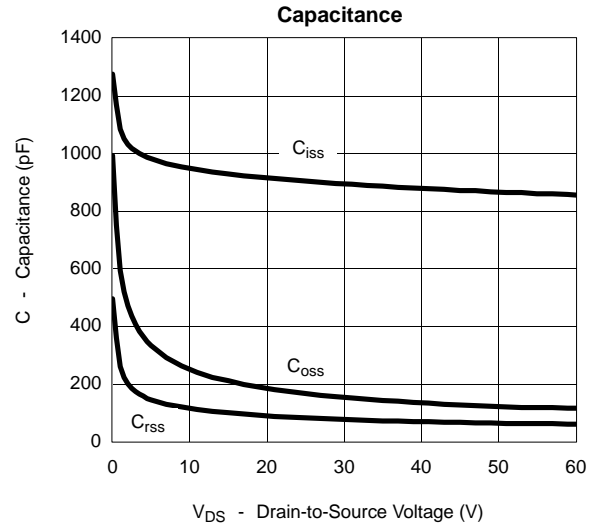
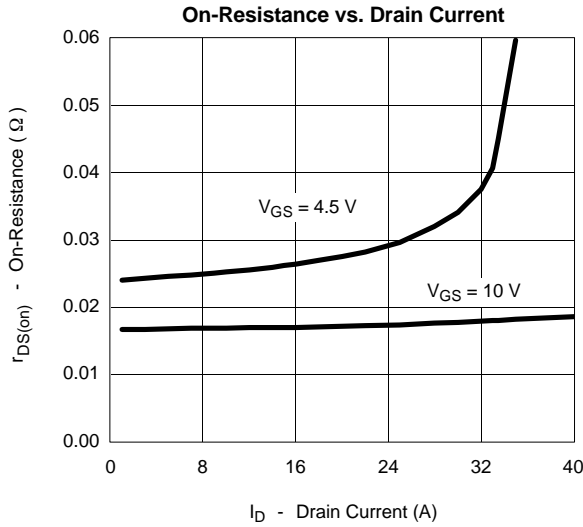
Notes

- a. Pulse test; pulse width $\leq 300\text{ }\mu\text{s}$, duty cycle $\leq 2\%$.
b. Guaranteed by design, not subject to production testing.

TYPICAL CHARACTERISTICS (25°C UNLESS NOTED)



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